

**Major Ratings and Characteristics**

$I_{F(AV)}$	3.0 A
$V_{RRM}$	20 V to 100 V
$I_{FSM}$	100 A
$V_F$	0.55 V, 0.70 V, 0.85V
$T_j \text{ max.}$	150 °C

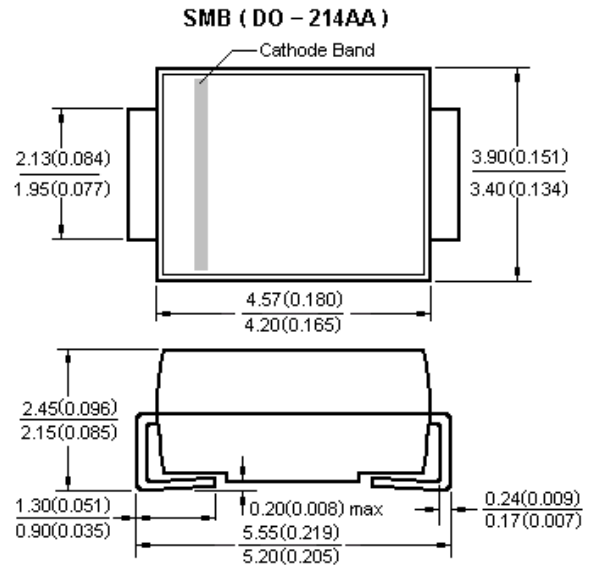


**Features**

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:  
260°C/10 seconds at terminals
- Component in accordance to  
RoHS 2002/95/1 and WEEE 2002/96/EC

**Mechanical Date**

- Case: JEDEC DO-214AA molded plastic body over passivated chip
- Terminals: Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity: Laser band denotes cathode end



Dimensions in millimeters and (inches)

**Maximum Ratings & Thermal Characteristics & Electrical Characteristics**

(TA = 25 °C unless otherwise noted)

	Symbol	SK32 SS32	SK33 SS33	SK34 SS34	SK35 SS35	SK36 SS36	SK38 SS38	SK310 SS310	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	30	40	50	60	80	100	V
Maximum RMS voltage	$V_{RMS}$	14	21	28	35	42	56	70	V
Maximum DC blocking voltage	$V_{DC}$	20	30	40	50	60	80	100	V
Maximum average forward rectified current	$I_{F(AV)}$	3							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	100							A
Maximum instantaneous forward voltage at 3.0A	$V_F$	0.55		0.70		0.85		V	
Maximum DC reverse current at Rated DC blocking voltage	$I_R$	$T_A = 25\text{ °C}$ 0.5							mA
		$T_A = 120\text{ °C}$ 5							mA
Voltage rate of change (rated VR)	dv/dt	10000							V/μs
Thermal resistance from junction to ambient	$R_{\theta JA}$	88							°C/W
Operating junction and storage temperature range	$T_J, T_{STG}$	- 65 to +150							°C

# SK32~SK310(SS32~SS310) SMB

Schottky rectifier



Characteristic Curves ( $T_A=25\text{ }^\circ\text{C}$  unless otherwise noted)

Fig.1 Forward Current Derating Curve

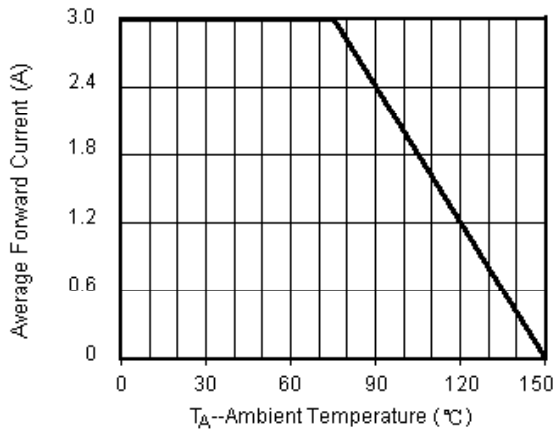


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

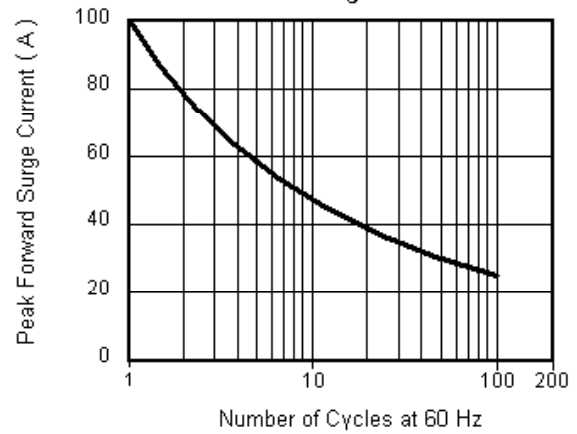


Fig.3 Typical Instantaneous Forward Characteristics

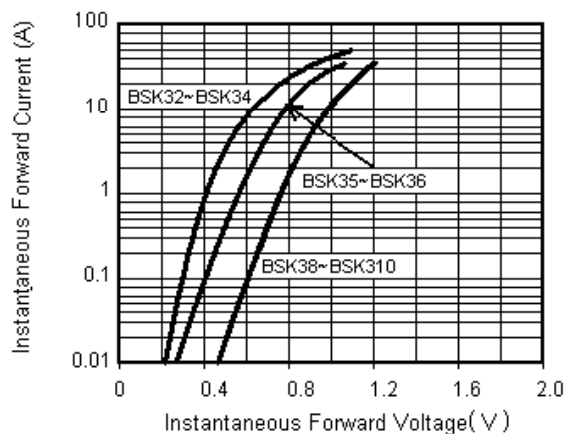


Fig.4 Typical Reverse Leakage Characteristics

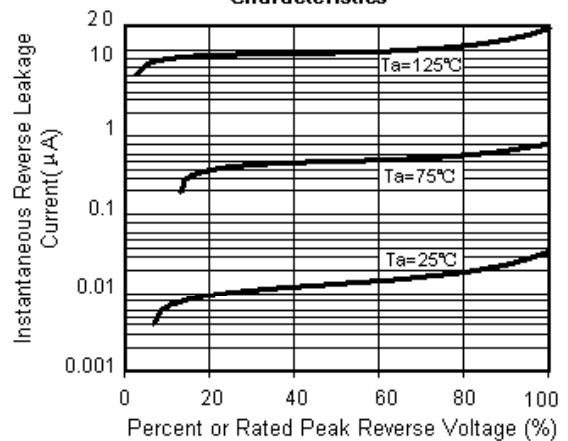


Fig.5 Typical Junction Capacitance

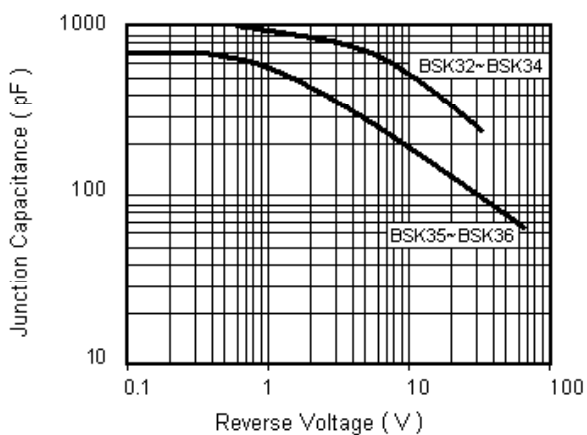


Fig.6 Transient Thermal Impedance

